



National Standards Authority of Ireland

TECHNICAL GUIDE

I.S. CLC/TR 62258-3:2007

ICS 31.080.99

**SEMICONDUCTOR DIE PRODUCTS -- PART
3: RECOMMENDATIONS FOR GOOD
PRACTICE IN HANDLING, PACKING AND
STORAGE (IEC/TR 62258-3:2005 (EQV))**

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CLC/TR 62258-3

February 2007

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Supersedes ES 59008-4-2:2000

English version

**Semiconductor die products –
Part 3: Recommendations for good practice in handling,
packing and storage
(IEC/TR 62258-3:2005)**

Halbleiter-Chip-Erzeugnisse –
Teil 3: Empfehlungen für die Praxis
bei Handhabung,
Verpackung und Lagerung
(IEC/TR 62258-3:2005)

This Technical Report was approved by CENELEC on 2006-12-12.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland and the United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Foreword

The text of the Technical Report IEC/TR 62258-3:2005, prepared by IEC TC 47, Semiconductor devices, was submitted to vote and was approved by CENELEC as CLC/TR 62258-3 on 2006-12-12.

This Technical Report supersedes ES 59008-4-2:2000.

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the Technical Report IEC/TR 62258-3:2005 was approved by CENELEC as a Technical Report without any modification.

In the official version, for Bibliography, the following note has to be added for the standard indicated:

IEC 62258-2	NOTE	Harmonized as EN 62258-2:2005 (not modified).
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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60050	Series	International Electrotechnical Vocabulary (IEV)	-	-
IEC 60286-3	- ¹⁾	Packaging of components for automatic handling - Part 3: Packaging of surface mount components on continuous tapes	EN 60286-3	1998 ²⁾
IEC 61340-5-1 + corr. February	1998 1999	Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena - General requirements	EN 61340-5-1 + corr. April	2001 2001
IEC 61340-5-2	1999	Electrostatics – Part 5-2: Protection of electronic devices from electrostatic phenomena - User guide	EN 61340-5-2 + corr. August	2001 2001
IEC 62258-1	- ¹⁾	Semiconductor die products – Part 1: Requirements for procurement and use	EN 62258-1	2005 ²⁾
ISO 14644-1	- ¹⁾	Cleanrooms and associated controlled environments – Part 1: Classification of air cleanliness	EN ISO 14644-1	1999 ²⁾

¹⁾ Undated reference.

²⁾ Valid edition at date of issue.

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